

Appl. No. 10/711,794
Amdt. dated May 26, 2006
Reply to Office action of January 27, 2006

Amendments to the Claims:

Listing of Claims:

Claim 1 (currently amended): A package structure comprising:

a lead frame having a plurality of first leads, each of which includes a first recession,

5 and a second recession;

at least a semiconductor chip; and

a plurality of first solder joints respectively positioned in the first recessions for connecting the semiconductor chip to the lead frame;

at least one passive device having a plurality of outputs respectively positioned in 10 the second recessions; and

a plurality of second solder joints respectively positioned in the second recessions for connecting the passive device to the lead frame.

Claim 2 (cancelled)

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Claim 3 (cancelled)

Claim 4 (currently amended): The package structure of claim 31 wherein the passive device is an electrical resistor, a capacitor, or an inductor.

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Claim 5 (cancelled)

Claim 6 (cancelled)

25 Claim 7 (cancelled)

Claim 8 (cancelled)

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Claim 9 (currently amended): The package structure of claim 31 wherein the second solder joints are comprised of tin or tin alloy.

5 Claim 10 (previously presented): The package structure of claim 1 wherein the lead frame comprises a die pad connected to the semiconductor chip for radiating the heat produced by the semiconductor chip by serving as a heat sink.

10 Claim 11 (previously presented): The package structure of claim 10 wherein the die pad comprises a ground pad connected to both ground and the semiconductor chip.

15 Claim 12 (previously presented): The package structure of claim 1 wherein the first solder joints are comprised of tin or tin alloy.

Claim 13 (currently amended): The package structure comprising:

15 a lead frame having a plurality of first leads, wherein at least two of the first leads comprises a first recession;

at least a passive device, wherein each output of the passive device is respectively positioned in the first recession; and

20 a plurality of first solder joints respectively positioned in the first recessions for connecting the passive device to the lead frame.

20 Claim 14 (previously presented): The package structure of claim 13 wherein the package structure further comprises a semiconductor chip and a plurality of leading wires, wherein the semiconductor chip is connected to the leading wires.

Claim 15 (previously presented): The package structure of claim 13 wherein the passive device is an electrical resistor, a capacitor, or an inductor.

25 Claim 16 (previously presented): The package structure of claim 13 wherein the first solder joints are comprised of tin or tin alloy.